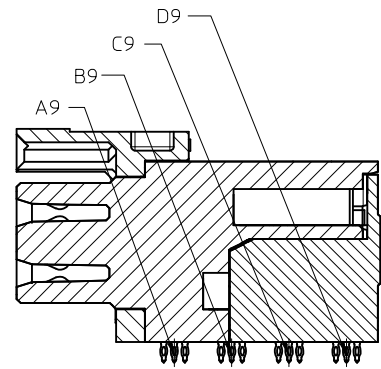
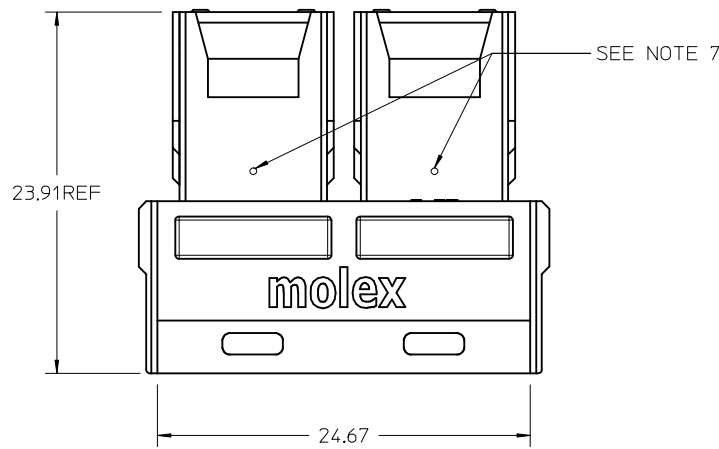
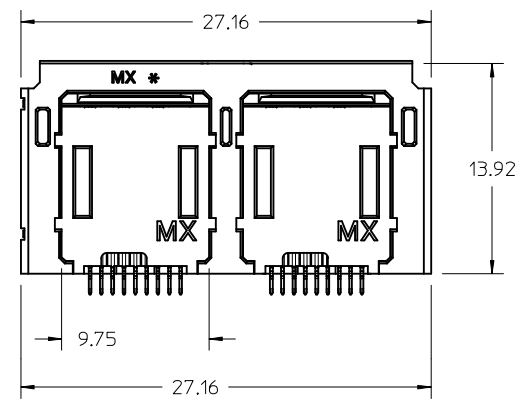
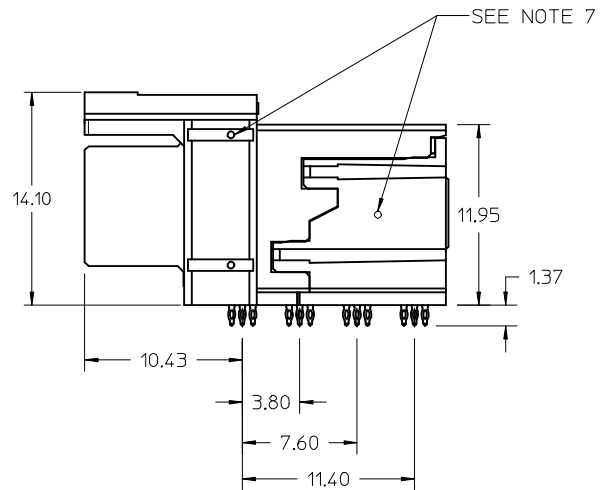
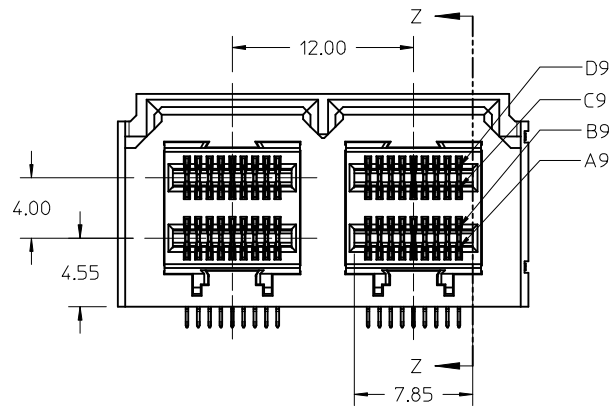
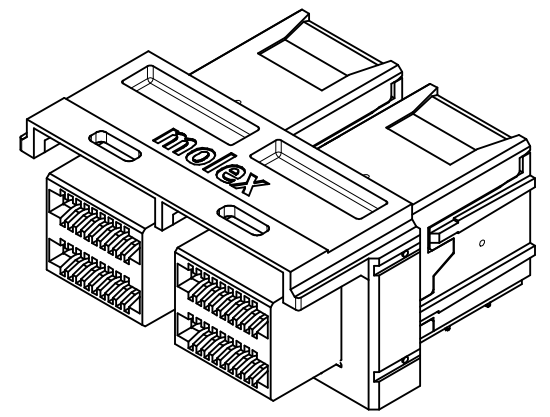


13 12 11 10 9 8 7 6 5 4 3 2 1



SECTION Z-Z



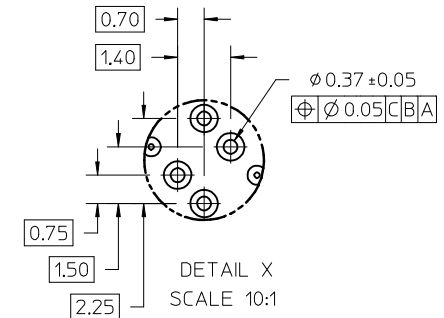
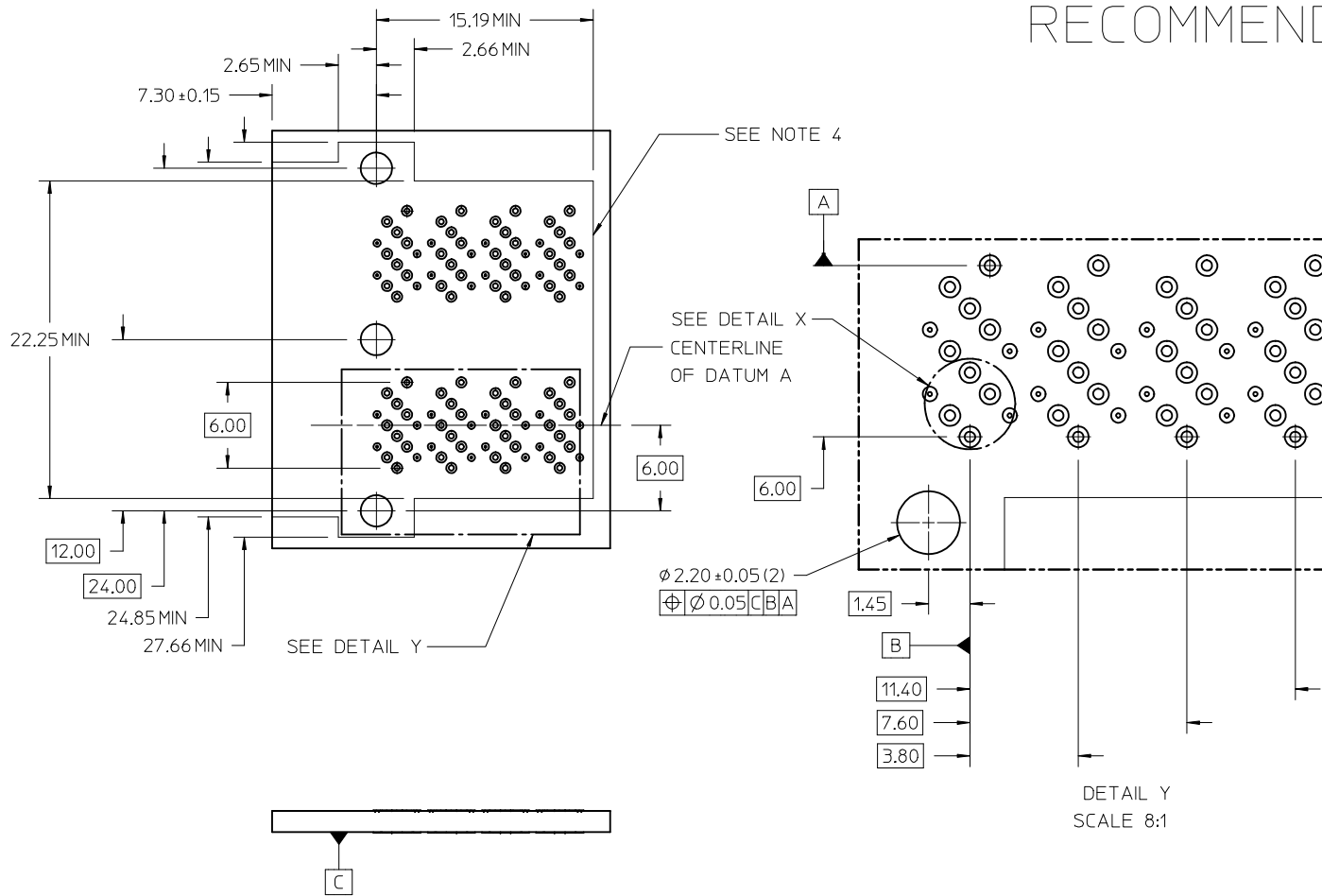
NOTES:

1. MATERIALS:
CONNECTOR HOUSING: HIGH TEMPERATURE THERMOPLASTIC
GLASS FILLED, UL 94V-0
TERMINALS: COPPER ALLOY
2. FINISHES:
CONTACT AREA: 0.76µM MIN GOLD OVER 2.54µM MIN NICKEL
TAIL AREA:
OPTION 1: 0.76µM-1.52µM TIN/LEAD (90/10) OVER 2.54µM MIN NICKEL
OPTION 2: 0.76µM-1.52µM TIN (LEAD FREE) OVER 2.54µM MIN NICKEL
3. PRODUCT SPECIFICATION: PS-76867-001
4. PACKAGING SPECIFICATION: PK-76867-001
5. MATES WITH: MOLEX CABLE SERIES 111067 & 111072
6. RECOMMENDED MOUNTING HARDWARE: M2X1.35 SELF-THREADING SCREW
MOUNTING SCREW LENGTH: PCB THICKNESS + 3.0MM MAX (1.75MM MIN)
MOUNTING HARDWARE NOT SUPPLIED
7. APPROXIMATE MOLDING GATE LOCATION

PLATING OPT.	MATERIAL NO.
OPTION 1	76867-0002
OPTION 2	76867-0012

REV NOTE REF SHT2 EC NO: UCP2013-1619 DRAWN BY: DRWNBKINGHAM 2012/10/25 CHKD: CHKD: 2012/10/29 APPR: TMCLELL 2012/10/29	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table><tr><th></th><th>mm</th><th>INCH</th></tr><tr><td>4 PLACES ±</td><td>---</td><td>---</td></tr><tr><td>3 PLACES ±</td><td>---</td><td>±.005</td></tr><tr><td>2 PLACES ±</td><td>0.13</td><td>±.010</td></tr><tr><td>1 PLACE ±</td><td>0.25</td><td>---</td></tr></table> ANGULAR ±1/2°		mm	INCH	4 PLACES ±	---	---	3 PLACES ±	---	±.005	2 PLACES ±	0.13	±.010	1 PLACE ±	0.25	---	DIMENSION STYLE MM ONLY DRAWN BY: KLANG DATE: 2009/05/15 CHECKED BY: DATE: APPROVED BY: MBANAKIS DATE: 2010/11/17 MATERIAL NO. SIZE: C	SCALE 4:1 TITLE IPASS PLUS HD 1X2 ASSEMBLY INTERNAL MOLEX INCORPORATED SD-76867-002 SHEET NO. 1 OF 4	DESIGN UNITS METRIC THIRD ANGLE PROJECTION
	mm	INCH																		
4 PLACES ±	---	---																		
3 PLACES ±	---	±.005																		
2 PLACES ±	0.13	±.010																		
1 PLACE ±	0.25	---																		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS																				
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																				

RECOMMENDED FOOTPRINT



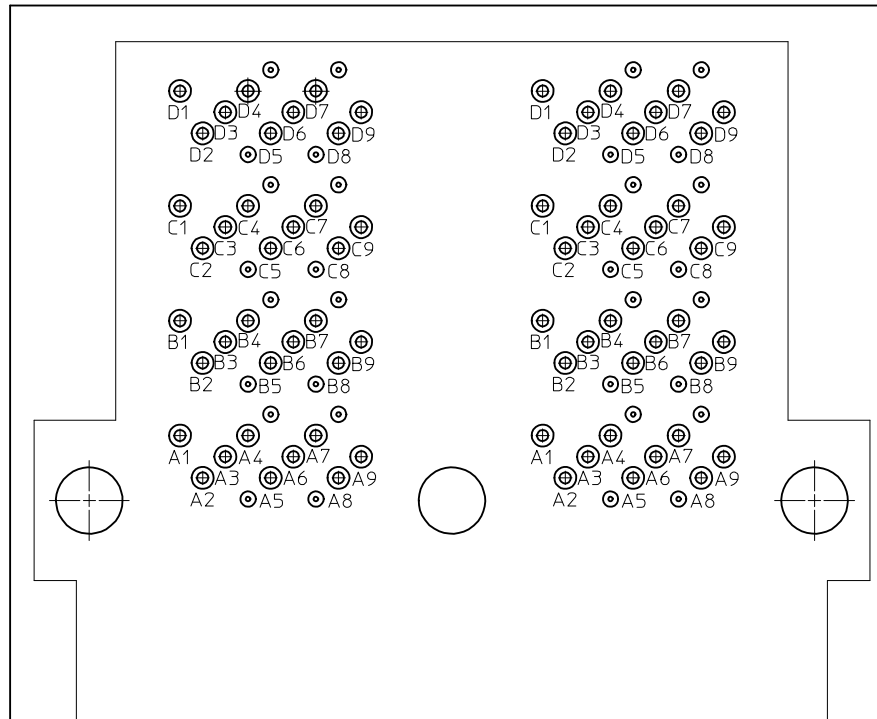
DETAIL Y
SCALE 8:1

NOTES:

1. RECOMMENDED DRILL SIZE AND ANNULAR RING FOR A 0.37 ϕ FINISHED PTH - REFER TO APPLICATION SPECIFICATION AS-76867-001
2. MINIMUM RECOMMENDED SPACING: 14.00MM
3. MINIMUM PCB THICKNESS: 1.57MM
4. CONNECTOR KEEP OUT AREA

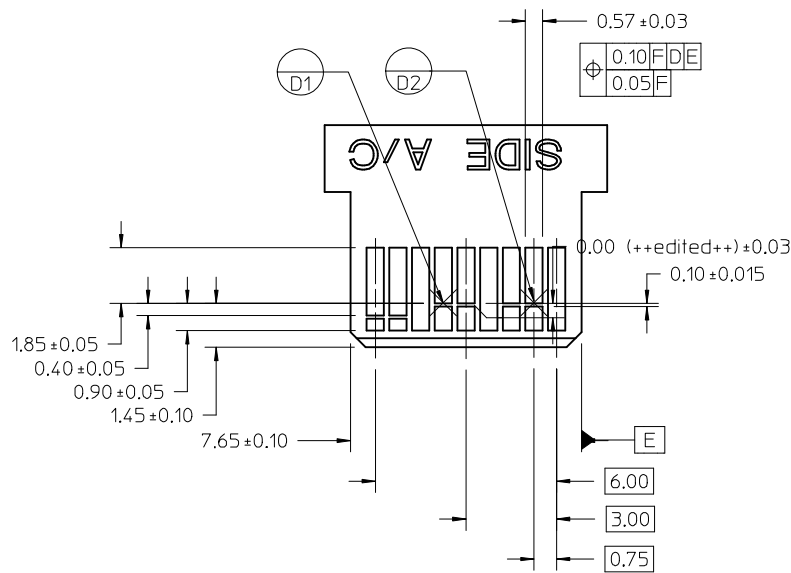
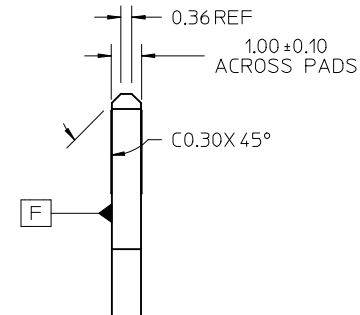
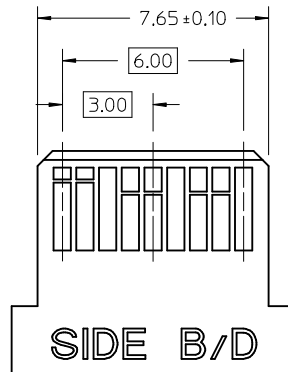
SEE SHEET 1 EC NO: UCP2013-1619 DRAWN BY: BINGHAM CHKD: APPR: TMCLELL REV: B8	DESCRIPTION 2012/10/25 2012/10/29	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
				mm	INCH	DRAWN BY KLANG	DATE 2009/05/15	TITLE IPASS PLUS HD 1X2 ASSEMBLY INTERNAL	
			4 PLACES ± --- ± ---	3 PLACES ± --- ± .005	CHECKED BY	DATE			
			2 PLACES ± 0.13 ± .010	APPROVED BY MBANAKIS		DATE 2010/11/17	 MOLEX INCORPORATED		
			1 PLACE ± 0.25 ± ---	MATERIAL NO.		DOCUMENT NO.		SHEET NO. 2 OF 4	
			ANGULAR ±1/2°		SEE CHART		SD-76867-002		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

FOOTPRINT CIRCUIT IDENTIFICATION



SEE SHEET 1 EC NO: UCP2013-1619 DRAWN BY: BINGHAM CHKD: APPR: TMCLELL REV	DESCRIPTION 2012/10/25 2012/10/29	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 8:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
				mm	INCH	DRAWN BY KLANG	DATE 2009/05/15	TITLE IPASS PLUS HD 1X2 ASSEMBLY INTERNAL	
			4 PLACES ± ---	± ---	CHECKED BY	DATE			
			3 PLACES ± ---	± .005	APPROVED BY MBANAKIS	DATE 2010/11/17	MOLEX MOLEX INCORPORATED		
			2 PLACES ± 0.13	± .010	MATERIAL NO.	DOCUMENT NO.			
			1 PLACE ± 0.25	± ---	SEE CHART		SD-76867-002	SHEET NO. 3 OF 4	
			ANGULAR ±1/2°		SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						

PLUG MODULE PCB LAYOUT



NOTES:

- 0.05 MINIMUM KEEP OUT FOR SOLDER MASK AROUND ALL PADS
- DATUM D TARGETS ARE DEFINED BY THE RESPECTIVE PAD CENTER LINES AND THE LEADING EDGE OF THE TARGET PADS

SEE SHEET 1
EC NO: UCP2013-1619
DRAWN BY: BINGHAM 2012/10/25
CHKD: TMCLELL 2012/10/29
APPR: TMCLELL 2012/10/29
REV B8

QUALITY SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .005
2 PLACES	± 0.13	± .010
1 PLACE	± 0.25	± ---

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY: KLANG DATE: 2009/05/15
CHECKED BY: DATE:

APPROVED BY: MBANAKIS DATE: 2010/11/17

MATERIAL NO. SEE SHEET 1

SCALE: 8:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

TITLE: IPASS PLUS HD 1X2 ASSEMBLY INTERNAL

MOLEX INCORPORATED

DOCUMENT NO. SD-76867-002

SHEET NO. 4 OF 4

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION